

Bill of Materials

CC2530 - CC2592EMK-RD

TI DESIGNS

Item	Qty	Reference	Value	Part Description	Manufacturer Part Number	PCB Footprint
1	1	A2	2.4GHz	MECHANIC, 2.4GHz INVERTED F ANTENNA, SMD	DN007	
2	2	C2 C5	2.2uF	CAPACITOR, CERAMIC X5R, 2.2uF, 10V, -20%/+20%, -55DEGC/+85DEGC, 0603, SMD	GRM188R61A225ME34D	0603
3	11	C4 C3051 C3061 C3071 C3081 C3102 C3109 C3111 C3133 C3134 C3135	DNM	CAPACITOR, DO NOT MOUNT, 0402, SMD	DNM	0402
4	5	C101 C211 C241 C271 C311	100nF	CAPACITOR, CERAMIC X7R, 100nF, 6.3V, -10%/+10%, -55DEGC/+125DEGC, 0402, SMD	GRM155R70J104KA01D	0402
5	4	C221 C231 C3106 C3131	12pF	CAPACITOR, CERAMIC C0G/NP0, 12pF, 50V, -5%/+5%, -55DEGC/+125DEGC, 0402, SMD	GRM1555C1H120JA01D	0402
6	1	C272	220pF	CAPACITOR, CERAMIC C0G/NP0, 220pF, 50V, -5%/+5%, -55DEGC/+125DEGC, 0402, SMD	GRM1555C1H221JA01D	0402
7	2	C321 C331	22pF	CAPACITOR, CERAMIC C0G/NP0, 22pF, 50V, -5%/+5%, -55DEGC/+125DEGC, 0402, SMD	GRM1555C1H220JA01D	0402
8	3	C391 C401 C3108	1uF	CAPACITOR, CERAMIC X5R, 1uF, 10V, -10%/+10%, -55DEGC/+85DEGC, 0402, SMD	GRM155R61A105KE15D	0402
9	1	C3101	1.8pF	CAPACITOR, CERAMIC C0G/NP0, 1.8pF, 50V, -0.25pF, +0.25pF, -55DEGC/+125DEGC, 0402, SMD	GRM1555C1H1R8CA01D	0402
10	1	C3103	2.2pF	CAPACITOR, CERAMIC C0G/NP0, 2.2pF, 50V, -0.25pF/+0.25pF, -55DEGC/+125DEGC, 0402, SMD	GRM1555C1H2R2CA01D	0402
11	1	C3105	1pF	CAPACITOR, CERAMIC C0G/NP0, 1pF, 50V, -0.25pF/ +0.25pF, -55DEGC/+125DEGC, 0402, SMD	GRM1555C1H1R0CA01D	0402
12	1	C3107	1nF	CAPACITOR, CERAMIC C0G/NP0, 1nF, 50V, -5%/+5%, -55DEGC/+125DEGC, 0402, SMD	CAPACITOR_0402_1nF_C0G/NP0_M +/-5%_50V	0402
13	1	C3110	18pF	CAPACITOR, CERAMIC C0G/NP0, 18pF, 50V, -55DEGC/+125DEGC, 0402, SMD	GRM1555C1H180JA01D	0402
14	1	C3132	1nF	CAPACITOR, CERAMIC X7R, 1nF, 50V, -5%/+5%, -55DEGC/+125DEGC, 0402, SMD	CAPACITOR_0402_1nF_X7R_M +/-5%_50V	0402
15	6	FIDU1 FIDU2 FIDU3 FIDU4 FIDU5 FIDU6	FIDU 1MM	FIDUCIAL MARK, ROUND 1MM		
16	2	FL1 FL2	BLM18HE152SN1	FILTER, EMI, 1500@100MHz, -55DEGC/+125DEGC, 0603, SMD	BLM18HE152SN1D	0603
17	1	J3	SMA-10V21-TGG	CONNECTOR, COAX RF, STRAIGHT, FEMALE, 1 PIN, SMD	SMA-10V21-TGG	
18	1	L3101	15nH	INDUCTOR, CHIP, 15nH, -5%/+5%, 0.3A, -55DEGC/+125DEGC, 0402, SMD	LQG15HS15NJ02D	0402
19	1	L3102	1nH	INDUCTOR, CHIP, 1nH, -0.3nH/+0.3nH, 0.3A, -55DEGC/+125DEGC, 0402, SMD	LQG15HS1N0S02D	0402
20	1	L3104	3nH	INDUCTOR, CHIP, 3nH, -0.3nH, +0.3nH, 0.3A, -55DEGC/+125DEGC, 0402, SMD	LQG15HS3N0S02D	0402
21	2	P1 P2	SFM-110-02-S-D-A-K-TR	CONNECTOR, HEADER, FEMALE, STRAIGHT, 2 ROWS, 20 PINS, PITCH 1.27mm, SMD	SFM-110-02-SM-D-A-K-TR	
22	1	R301	56k	RESISTOR, THICK FILM, 56k, -5%/+5%, 0.063W, 50V, -55DEGC/+155DEGC, 0402, SMD	CRCW040256K0JNED	0402
23	3	R3051 R3061 R3071	10k	RESISTOR, THICK FILM, 10k, -5%/+5%, 0.063W, 50V, -55DEGC/+155DEGC, 0402, SMD	CRCW040210K0JNED	0402
24	1	R3081	3.9k	RESISTOR, THICK FILM, 3.9k, -1%/+1%, 0.1W, 50V, -55DEGC/+155DEGC, 0402, SMD	ERJ2RKF3901X	0402
25	3	RP07 RP10 RP11	DNM	RESISTOR, THICK FILM, 0, -0/+0.02R, 0.1W, -55DEGC/+155DEGC, 0402, SMD	RESISTOR_0402_0_50V_0.1W_M_DNM	0402
26	1	RP12	0	RESISTOR, THICK FILM, JUMPER, 0/+0.05R, 0.063W, 50V, -55DEGC/+155DEGC, 0402, SMD	RK73Z1ETTP	0402
27	1	SC1	BMI-S-209-F	MACHANIC, STANDARD SURFACE MOUNT SHIELD FRAMES, TWO PIECE, SMD	BMI-S-209-F	
28	1	U5	CC2592	IC, ANALOG, 2.4GHz RF FRONT END, 2V TO 3.7V, QFN16, SMD	CC2592	QFN16
29	1	U7	CC2530F256	IC, ANALOG, A TRUE SYSTEM-ON-CHIP SOLUTION FOR 2.4GHz IEEE 802.15.4 AND ZigBee APPLICATIONS, 250KB, 2V TO 3.6V, VQFN40, SMD	CC2530F256RHAR	VQFN40
30	1	Y1	32MHz	CRYSTAL, OSCILATOR, 32MHz, 10pF, -10PPM/+10PPM, -40DEGC/+85DEGC, SMD	FA-128 32MHz 10pF 10PPM	SMD
31	1	Y2	32.768kHz	CRYSTAL, OSCILATOR, 32.768kHz, -20PPM/ +20PPM, -40DEGC/ +85DEGC, 12.5pF, SMD	FC-12M 32.7680KA-A3	

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